



# 10-Bit Current output D to A Converter

## DAC100

### 1.0 SCOPE

This specification documents the detail requirements for space qualified product manufactured on Analog Devices, Inc.'s QML certified line per MIL-PRF-38535 Level V except as modified herein. The manufacturing flow described in the STANDARD SPACE LEVEL PRODUCTS PROGRAM brochure is to be considered a part of this specification. This brochure can be found at:

<http://www.analog.com/aerospace>

This data sheet specifically details the space grade version of this product. A more detailed operational description and a complete data sheet for commercial product grades can be found at [www.analog.com/DAC100](http://www.analog.com/DAC100)

### 2.0 Part Number. The complete part number(s) of this specification follow:

<u>Part Number</u>	<u>Description</u>
<b>DAC100-703Q</b>	10-Bit Current output D to A Converter
<b>DAC100-713Q</b>	Radiation tested, 10-Bit Current output D to A Converter

### 2.1 Case Outline.

<u>Letter</u>	<u>Descriptive designator</u>	<u>Case Outline (Lead Finish per MIL-PRF-38535)</u>
Q	GDIP1-T16	16-Lead ceramic dual-in-line package (CERDIP)

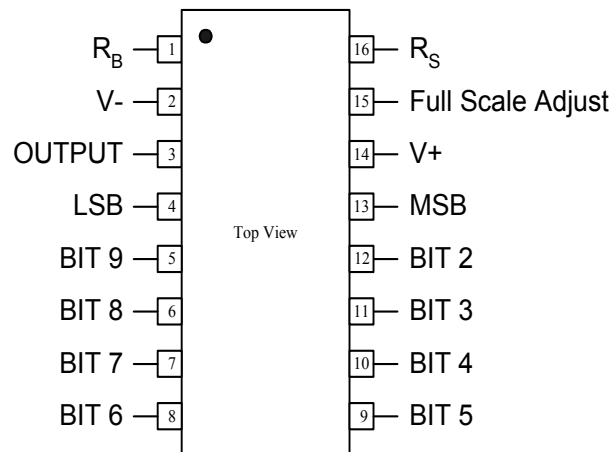
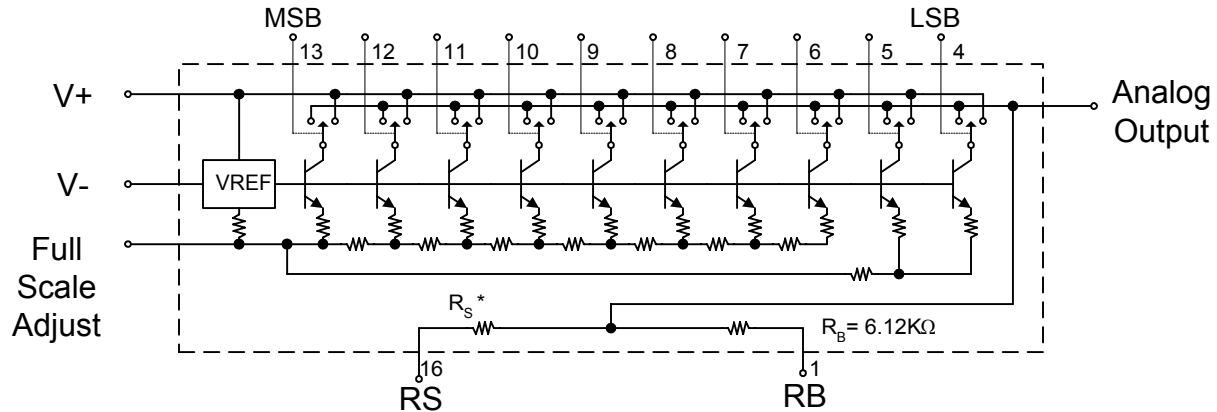


Figure 1 - Terminal connections.

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$R_S = 4.88K\Omega$

Figure 1A: Simplified schematic

### 3.0 Absolute Maximum Ratings. ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

V+ supply to V- supply.....	0V to 36V
V+ supply to output.....	0V to +18V
V- supply to output.....	0V to -18V
Power dissipation .....	500mW
Logic inputs to outputs.....	-1V to +6V
Operating temperature range.....	-55°C to +125°C
Storage temperature range.....	-65°C to +150°C
Lead temperature (soldering, 60 sec.) .....	+300°C
Dice junction temperature ( $T_J$ ).....	+175°C

### 3.1 Thermal Characteristics:

Thermal resistance, CERDIP (Q) Package	
Junction-to-case ( $\Theta_{JC}$ ) =	29°C/W Max
Junction-to-ambient ( $\Theta_{JA}$ ) =	91 °C/W Max
Thermal resistance, FLATPAK (N) Package	
Junction-to-case ( $\Theta_{JC}$ ) =	22°C/W Max
Junction-to-ambient ( $\Theta_{JA}$ ) =	90 °C/W Max

4.0 **Electrical Table:** See notes at end of table

TABLE I						
Parameter	Symbol	Conditions <u>1/</u>	Sub-group	Limit Min	Limit Max	Units
Power supply current	I+	V <sub>IH</sub> = 2.1V	1, 2, 3		8.33	mA
	I-	V <sub>IH</sub> = 2.1V	1, 2, 3		8.33	
Full range output voltage	V <sub>FR</sub>	V <sub>IL</sub> = 0.7V, Full Adjust pin tied to V-	1, 2, 3	10.0	11.1	V
Zero scale output voltage	V <sub>ZS</sub>	V <sub>IH</sub> = 2.1V	1, 2, 3		±0.13	%FS
Integral nonlinearity	NL	± ½ LSB – 9 Bits	1, 2, 3		±0.1	
Full scale temperature coefficient	TCV <sub>FR</sub>	V <sub>IL</sub> = 0.7V, Full Scale Adjust pin tied to V-	8		±60	ppm/°C
Logic inputs high	V <sub>IH</sub>	V <sub>IN</sub> = 2.1V to 3V (all inputs) Measured with respect to output pin allowing ≤ ±½ LSB change with ΔV <sub>IN</sub>	1, 2, 3	2.1		V
Logic inputs low	V <sub>IL</sub>	V <sub>IN</sub> = 0.7V to 0V (all inputs) Measured with respect to output pin allowing ≤ ±½ LSB change with ΔV <sub>IN</sub>	1, 2, 3		0.7	
Logic input current high	I <sub>IH</sub>	V <sub>IH</sub> = 6.0V, Each Input	1, 2, 3		5	μA
Logic input current low	I <sub>IL</sub>	V <sub>IL</sub> = 0V, Each Input	1, 2, 3		5	
Power supply sensitivity	PSS	V <sub>IL</sub> = 0.7V (all inputs) V <sub>S</sub> = ±6V to ±18V	1, 2, 3		±0.1	%/V
Monotonicity <u>2/</u>	ΔI <sub>O</sub>	Measured at each major carry code point	1	0		μA
Settling time <u>3/</u>	T <sub>SHL</sub>	R <sub>L</sub> = 1KΩ, C <sub>L</sub> ≤ 10pF	9		375	nS

Table I notes:

1/ V<sub>S</sub> = ±15V, unless otherwise specified.

2/ The change in output current either increases or remains the same for an increasing digital input code.

3/ Output within ± ½ LSB of 10-bit accuracy final settled nominal value of V<sub>OUT</sub>.

Input pulse characteristics:

Input frequency = 1MHz square wave, 50% duty cycle.

Input amplitude = 0V to 2.1V

Input signal = t<sub>r</sub>, t<sub>f</sub> ≤ 20 nS

Measurement referenced to input High-to-Low Transition. DUT Settling Time to ±0.05 % FS

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## 4.1 Electrical Test Requirements:

<b>Table II</b>	
MIL-STD-883 Test Requirements	Subgroups (see table I)
Interim electrical parameters (pre Burn-In)	1
Final Electrical Test Parameters	1, 2, 3, 8 <u>1/</u> <u>2/</u>
Group A Test Requirements	1, 2, 3, 8, 9
Group C Test Requirements	1 <u>2/</u>
Group D Test Requirements	1
* PDA applies to Subgroup 1 only. No other subgroups are included in PDA.	

1/ PDA applies to subgroup 1. Deltas not included in PDA

2/ See table III for deltas. See table I for test conditions.

## 4.2 Table III. Burn-in test delta limits.

<b>Table III</b>				
TEST TITLE	BURN-IN ENDPOINT	LIFETEST ENDPOINT	DELTA LIMIT	UNITS
V <sub>FR</sub>	10.55 ± 0.55	10.55 ± 0.75	±0.2	V
V <sub>ZS</sub>	±0.013	±0.018	±0.005	%FS
I+	8.33	8.33	±10%	mA
I-	8.33	8.33	±10%	mA

## 5.0 Life Test/Burn-In Circuit:

- 5.1 HTRB is not applicable for this drawing.
- 5.2 Burn-in is per MIL-STD-883 Method 1015 test condition B.
- 5.3 Steady state life test is per MIL-STD-883 Method 1005.

Rev	Description of Change	Date
A	Initiate	30-Jun-00
B	Update web address	Feb. 18, 2002
C	Update web address. Add Group C and D to table II. Add life test endpoint based on delta to table III.	Feb. 28, 2003
D	Delete Burn-In circuit	Aug. 5, 2003
E	Update header/footer & add to 1.0 Scope description	Feb. 21, 2008
F	Remove minimum Dice Junction Temp. range in 3.0 Absolute Max. Ratings	March 31, 2008

